FILED UNDER 35 U.S.C. 371

PATENT NUMBER and ISSUE DATE

U.S. UTILITY Patent Application

1	APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU,	2818	EXAMI	NER				
-	10070080	07/01/2002	257(1701	1744	TR	-11 TT L	<u>).</u>	Ntm			
	**APPLICANTS: Do Bento Vieira Antonio;											
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	**CONTINUING DATA VERIFIED: THIS APPLICATION IS A 371 OF PCT/FR09/02367 08/24/2000											
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	Foreign priority cla 35 USC 119 cond	litions met	□ y	es □ no es □ no		- 1	R2-144	ZINE 1 180				
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TITLE: Method for packaging a semiconductor chip containing sensors and resulting package U.S.DEPT, OF COMM./PAT.& TM-PTO-436L(Rev. 12-94)												

NOTICE OF ALL	OWANCE MAILED		CLAIMS ALLOWED						
		Assistant Examiner	Total Claims		Print Claim for O.G				
188	UE FEE		DRAWING						
Amount Due	Date Paid	7	Sheets Drwg.	Figs.Drwg.	Print Fig.				
		Primary Examiner		ł					
TEF	RMINAL	PREPARED FOR ISSUE	Application Examiner						
	DISCLAMER	WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.							
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(Attached in pocket on right inside flap)